## Claims

We claim:

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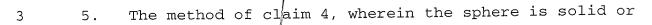
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- 1 1. A method for making a conductive path in a laminate 2 structure hole comprising the steps of:
  - providing a laminate with a top surface and a bottom surface and having at least one hole;
- 5 providing a conductive element;
  - inserting the conductive element into the at least one hole in the laminate; and
    - deforming the conductive element within the at least one hole in the laminate to retain the conductive element within the at least one hole.
    - 2. The method of claim 1, wherein the deforming of the conductive element further includes forming an electrode at the top surface of the laminate.
  - 3. The method of claim 1, wherein the at least one hole is a through hole extending from the top surface to the lower surface of the laminate.
- 1 4. The method of claim 1, wherein the conductive element is a sphere.

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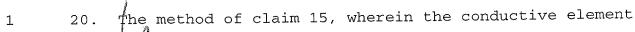


- 4 hollow.
- 1 6. The method of claim 1, wherein the at least one hole is
- 2 a blind via.
- 1 7. The method of claim 1, wherein the conductive element
- 2 includes a conductive surface covering a base element.
  - 8. The method of claim 7, wherein the conductive surface is selected from the group consisting of copper, brass, gold, and bronze.
  - 9. The method of claim 7, wherein the base element is selected from the group consisting of glass, rubber, and plastic.
- 1 10. The method of claim 1, wherein the conductive element is
- 2 a cylinder.
- 1 11. The method of claim 10, wherein the cylinder is solid or
- 2 hollow.

- 1 12. The method of claim 1, wherein the conductive element is
- selected from the group consisting of copper, brass, gold,
- 3 and bronze.
- 1 13. The method of claim 1, wherein the at least one hole is
- 2 a buried via.

- 1 14. A method comprising:
- 2 embedding a conductive element into a laminate, wherein
- 3 the conductive element substantially maintains a shape while
- 4 the laminate deforms to accommodate the conductive element.
- 1 15. The method of claim 14, wherein the conductive element
- 2 includes a conductive surface covering a base element.
- 1 16. The method of claim 15, wherein the conductive surface
  - is selected from the group consisting of copper, brass, gold,
    - and bronze.
    - 17. The method of claim 15, wherein the base element is
    - selected from the group consisting of glass, rubber, and
    - plastic.

- 18. The method of claim 15, wherein the conductive element
- 2 is selected from the group consisting of copper, brass, gold,
- 3 and bronze.
- 1 19. The method of claim 15, wherein the conductive element
- 2 is a sphere or a cylinder.



2 is hollow.

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- 21. A method comprising:

  providing an opening in a laminate; and

  pressing a conductive element into the opening.
- 1 22. The method of claim 21, wherein the opening is a hole.
- 1 23. The method of claim 21, wherein the conductive element
  - 24. The method of claim 21, wherein the conductive element is a cylinder.

is a sphere.

1	25. A method comprising:
2	providing a plurality of laminates;
3	embedding at least one conductive element into each
4	laminate;
5	forming a contact pad on each end of each conductive
6	element;
7	bonding each laminate together to form a stack; and
8	wherein adjoining contact pads press together and form
9	an electrical connection.
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	26. The method of claim 25, further including a conductive
<u>2</u>	adhesive applied between adjoining contact pads.
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27. A structure comprising:

a conductive element embedded into a laminate.

- The structure of claim 27, further including an opening in the laminate that the conductive object is pressed into.
- The structure of claim 28, wherein the opening is a hole 1 2 in the laminate.
  - The structure of claim 27, wherein the conductive element is a sphere or a dylinder.
  - The structure of claim 27, wherein the conductive 31. element is selected from the group consisting of copper, brass, and bronze.
  - The structure of claim 27, wherein the laminate is selected from the group consisting of epoxy, cyanate-epoxy blend, and glass reinforced carrier.